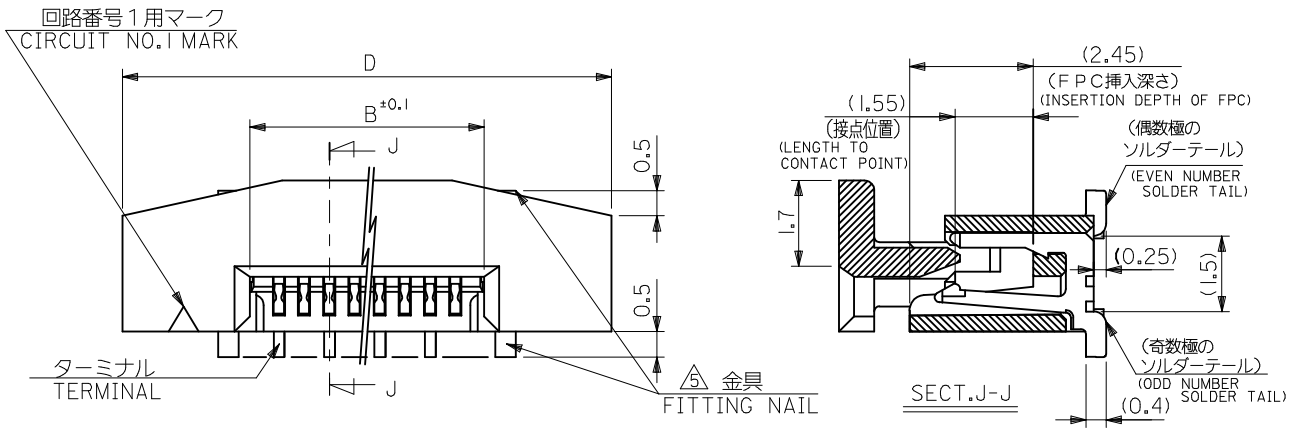

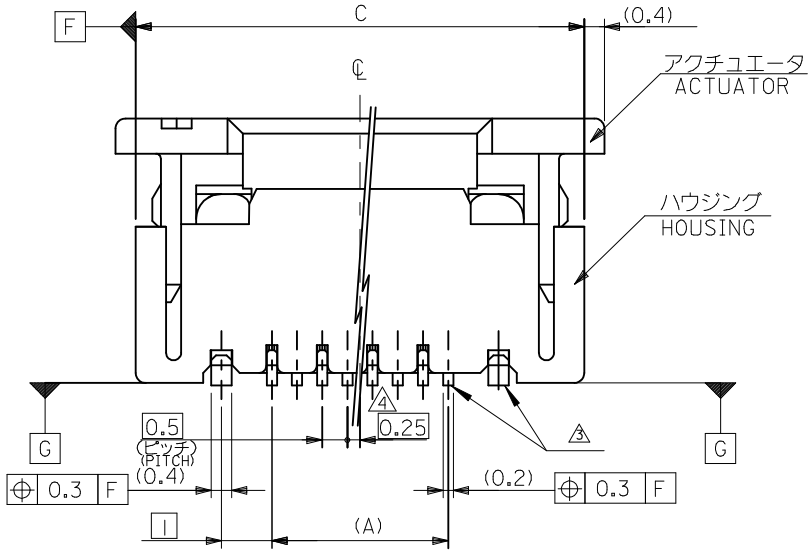

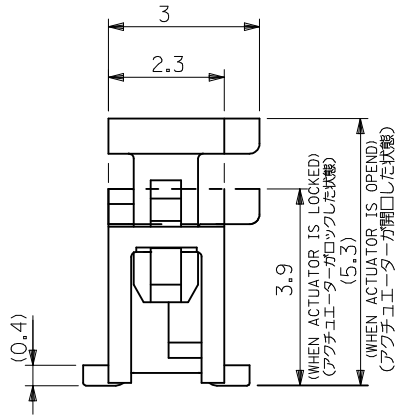

注記 NOTES

1. 材質 MATERIAL
   ハウジング：ポリアミド（PA）、ガラス充填、ナチュラル（白）、UL94V-0
   HOUSING : POLYAMIDE , GLASS FILLED, NATURAL, UL94V-0
   アクチュエータ：ポリフェニレンサルファイド(PPS)、ガラス充填、ナチュラル、UL94V-0
   ACTUATOR : POLYPHENYRENE SULFIDE, GLASS FILLED, NATURAL(BROWN), UL94V-0
   ターミナル：銅合金（t = 0.2）
   TERMINAL : COPPER ALLOY (t = 0.2)
   金具：銅合金（t = 0.4）
   NAIL : COPPER ALLOY (t = 0.4)
2. めっき仕様 PLATING
   ターミナル TERMINAL
   錫銀ビスマスめっき(1.0 μm以上)
   下地：ニッケルめっき（1.0 μm以上）
   TIN SILVER BISMUTH PLATING
   (1.0 MICROMETER MINIMUM)
   UNDER PLATE : NICKEL PLATING
   (1.0 MICROMETER MINIMUM)
   金具 FITTING NAIL
   錫めっき（1.0 μm以上）
   下地：ニッケルめっき（1.0 μm以上）
   TIN PLATING
   (1.0 MICROMETER MINIMUM)
   UNDER PLATE : NICKEL PLATING
   (1.0 MICROMETER MINIMUM)

3 ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 G に対し上方向0.05MAXIMUM、下方向0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM G
UPPER DIRECTION : 0.05MAXIMUM
LOWER DIRECTION 0.15MAXIMUM.

4 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

5 パターンはくり止め用金具。
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

6 R0.3は、ＦＰＣの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

7. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO. 52559-**22 SHOULD BE LOCKED.

8. ソルダーテールの平坦度は、0.12 MAXIMUMとする。
SOLDER TAIL COPLANARITY IS 0.12 MAXIMUM.

9. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.

REVISED
EC NO: J2013-1168 2013/03/19
DRWN:NKONDO 2013/03/19
CH'KD:KTAKAHASHI 2013/04/25
APPR:KMORIKAWA DESCRIPTION
A REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	AISHI 2012/09/05
CHECKED BY / DATE	KTAKAHASHI 2012/09/05
APPROVED BY / DATE	KMORIKAWA 2013/03/15
MATERIAL NO.	SEE CHART
TITLE	0.5MM FPC CONN ZIF S/T HOUSING ASSY
DOCUMENT NO.	SD-52559-057
SHEET NO.	1 OF 2
SIZE	A3

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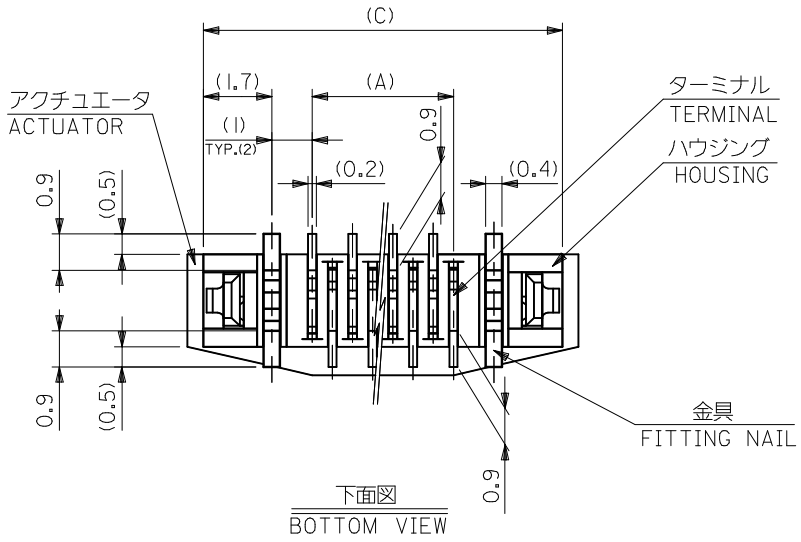
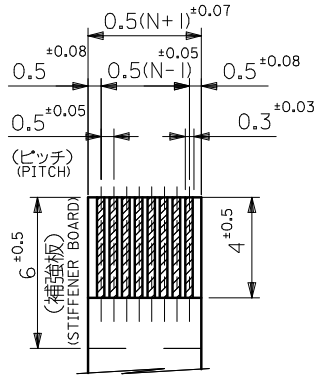
FPC/FFCについて ABOUT FPC/FFC

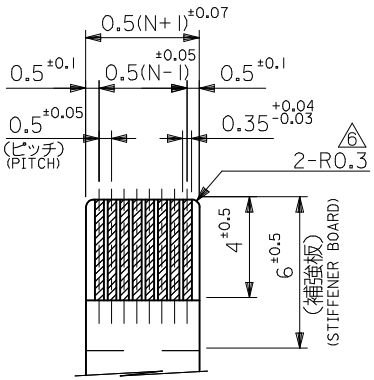
打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟箔銅35μmまたは50μmを推奨します。
RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER

FPCについてABOUT FPC
補強フィルム材質はポリイミドを推奨します。ベースフィルムは
25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

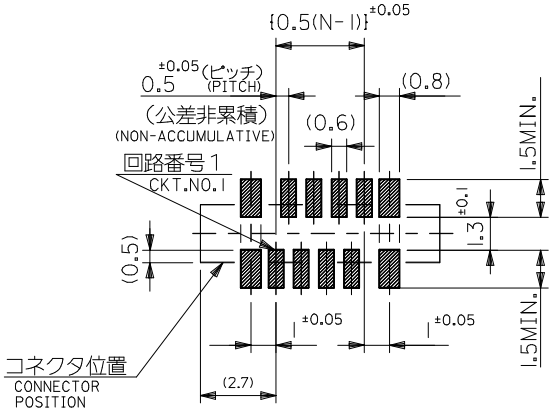




適合FFC推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION.
(仕上がり厚さ：$0.3^{\pm0.05}$)
(THICKNESS:$0.3^{\pm0.05}$)

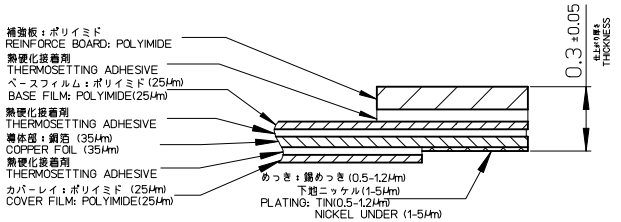


適合FPC推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION.
(仕上がり厚さ：$0.3^{\pm0.05}$)
(THICKNESS:$0.3^{\pm0.05}$)



推奨基板レイアウト
(マウント面)
RECOMMENDED P.C.BOARD PATTERN DIMENSION (MOUNTING SIDE)

マスク厚　：　150μm
マスク開口率　：　100%
SCREEN THICKNESS　：150μm
SCREEN OPEN RATIO：100%



FPC構成推奨仕様
STRUCTURE OF FPC

D	C	B	(A)	EMBOSSED PACKAGE ORDER No.		極数 CKT.
26.7	25.9	21.65	20.5	52559-4233		42
25.7	24.9	20.65	19.5	52559-4033		40
23.7	22.9	18.65	17.5	-3633		36
22.2	21.4	17.15	16.0		-3334	33
21.7	20.9	16.65	15.5	-3233		32
20.7	19.9	15.65	14.5	-3033		30
19.7	18.9	14.65	13.5	-2833	-2834	28
19.2	18.4	14.15	13.0	-2733		27
18.7	17.9	13.65	12.5	-2633		26
18.2	17.4	13.15	12.0		-2534	25
17.7	16.9	12.65	11.5	-2433	-2434	24
17.2	16.4	12.15	11.0	-2333		23
16.7	15.9	11.65	10.5		-2234	22
16.2	15.4	11.15	10.0	-2133		21
15.7	14.9	10.65	9.5	-2033	-2034	20
14.7	13.9	9.65	8.5		-1834	18
14.2	13.4	9.15	8.0	-1733		17
13.7	12.9	8.65	7.5	-1633	-1634	16
13.2	12.4	8.15	7.0	-1533		15
12.7	11.9	7.65	6.5	-1433	-1434	14
12.2	11.4	7.15	6.0		-1334	13
11.7	10.9	6.65	5.5	-1233		12
10.7	9.9	5.65	4.5	-1033		10
10.2	9.4	5.15	4.0	-0933		9
9.7	8.9	4.65	3.5		-0834	8
8.7	7.9	3.65	2.5	52559-0633		6

CONNECTOR SERIES NO. : 52559-**22

REVISED
EC NO: J2013-1168 2013/03/15
DRWN:NKONDO 2013/03/19
CHKD:KTAKAHASHI 2013/04/25
APPR:KMORIKAWA DESCRIPTION
A REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	AISHII 2012/09/05
CHECKED BY / DATE	KTAKAHASHI 2012/09/05
APPROVED BY / DATE	KMORIKAWA 2013/03/15
MATERIAL NO.	SEE CHART
TITLE	0.5MM FPC CONN ZIF S/T HOUSING ASSY
DOCUMENT NO.	SD-52559-057
SHEET NO.	2 OF 2
SIZE	A3

molex

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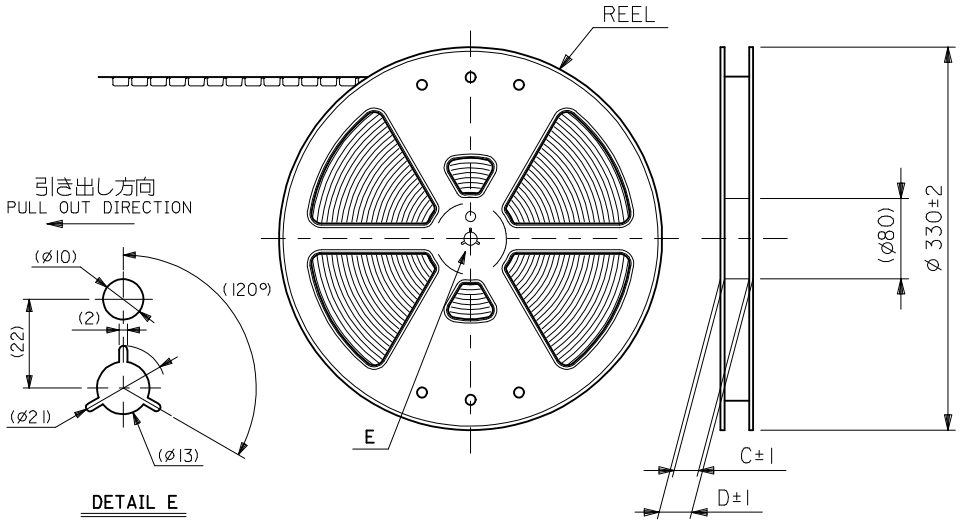
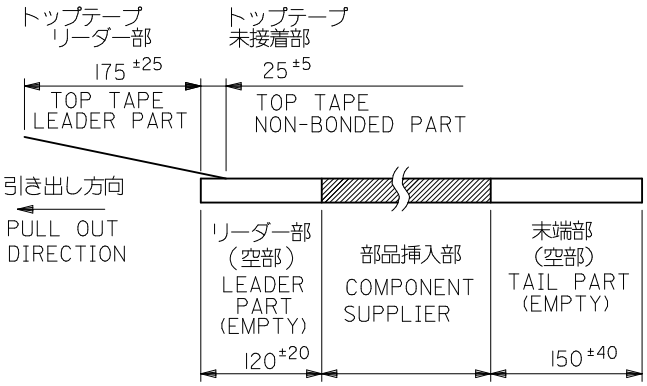


DETAIL E

注記 NOTES

1. 製品番号52559-**22の梱包状態は、アクチュエータをロックした状態とする。
詳細寸法については、図面SD-52559-057を参照ください。
IN THE PACKAGE,ACTUATOR OF PART NO.52559-**22 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52559-057.
2. 梱包数量：1000個／リール
NUMBER OF CONNECTORS:1000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

5. 材料 キャリアテープ：ポリプロピレン（ＰＰ）
トップテープ：ＰＥＴ，ＰＥ，ＰＥＦ
リール：ポリスチレン（ＰＳ）<リサイクル材を含む>
MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED				REV
EC NO: J2013-1168	DRWN:NASANUMA	CH'KD:KTAKAHASHI	APPR:KMORIKAWA	DESCRIPTION
2013/04/16	2013/04/16	2013/04/25		
A				

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	NASANUMA
DATE	2013/02/23
CHECKED BY	KTAKAHASHI
DATE	2013/02/25
APPROVED BY	KMORIKAWA
DATE	2013/03/15
MATERIAL NO.	SEE CHART
SIZE	A3

MODEL NO.	52559-**34
TITLE	EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF/ S/T HOUSING ASSY
	molex
DOCUMENT NO.	SD-52559-059
SHEET NO.	1 OF 3

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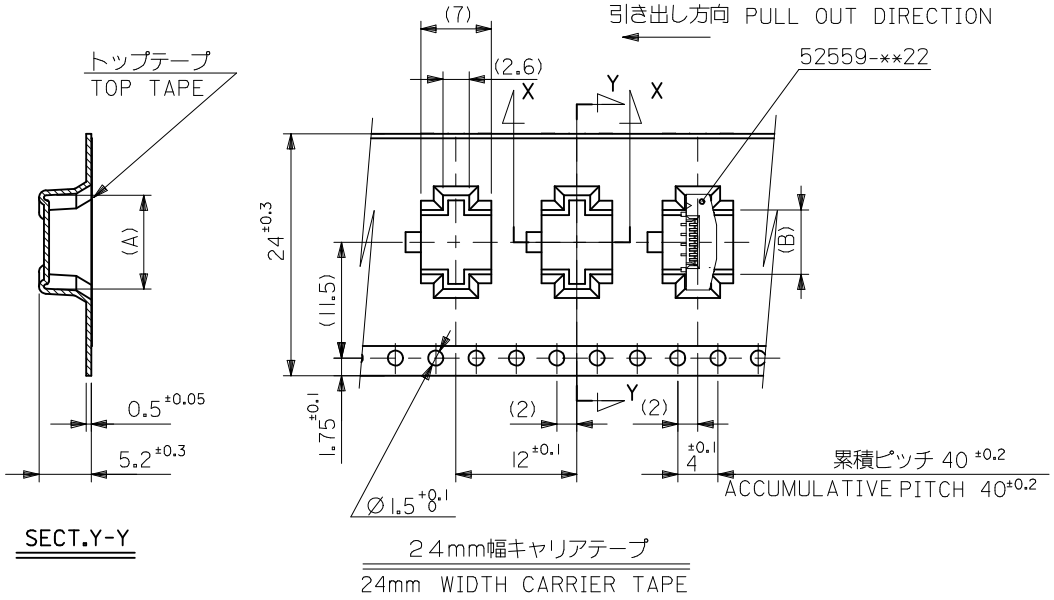

MODEL No.52559-**34	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
	24	29.4	25.4	13.4	16.3	52559-2234	22
				12.4	15.3	52559-2034	20
				11.4	14.3	52559-1834	18
				10.4	13.3	52559-1634	16
				9.4	12.3	52559-1434	14
				8.9	11.8	52559-1334	13
				6.4	9.3	52559-0834	8

SEE SHEET 1 OF 3
EC NO: J2013-1168 2013/04/16
DRWN:NASANUMA 2013/04/16
CH'KD:KTAKAHASHI 2013/04/25
APPR:KMORIKAWA
DESCRIPTION
REV A

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: NASANUMA DATE: 2013/02/23
CHECKED BY: KTAKAHASHI DATE: 2013/02/23
APPROVED BY: KMORIKAWA DATE: 2013/03/15
MATERIAL NO.: SEE CHART

TITLE: EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF S/T HOUSING ASSY

molex

DOCUMENT NO.: SD-52559-059
SHEET NO.: 2 OF 3
SIZE: A3

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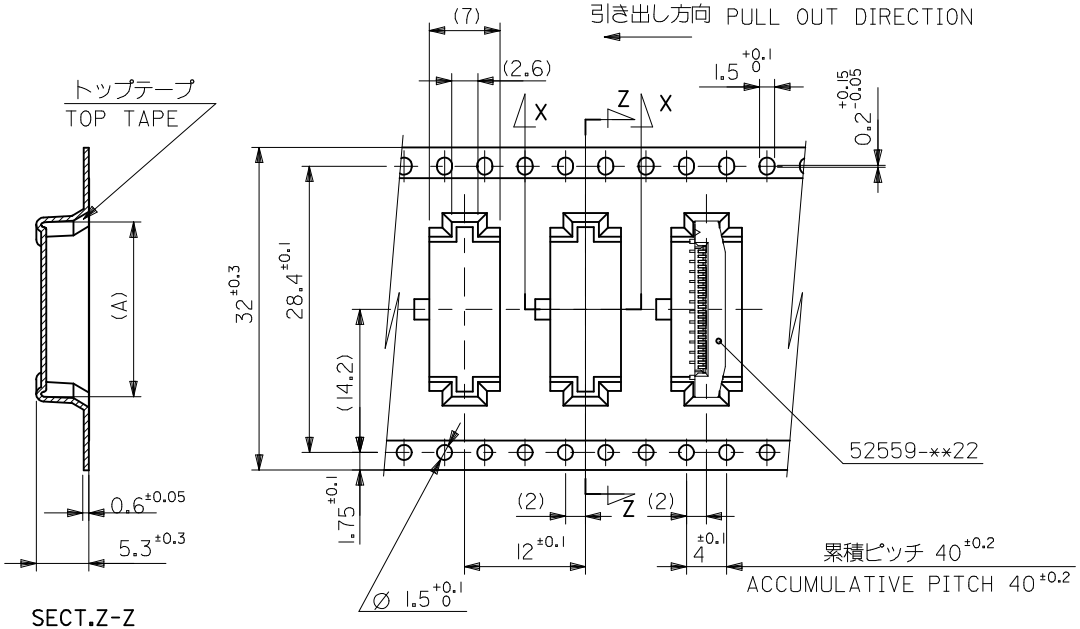
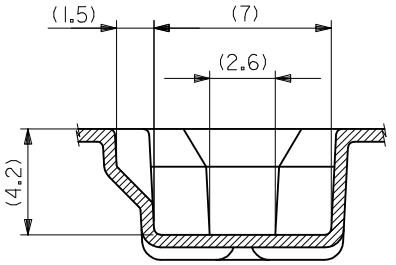


SECT.Z-Z



SECT.X-X

32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

MODEL No.52559-**34	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
	32	37.4	33.4	18.9	21.8	52559-3334	33
				16.4	19.3	52559-2834	28
				14.9	17.8	52559-2534	25
				14.4	17.3	52559-2434	24

SEE SHEET 1 OF 3
EC NO: J2013-1168
DRWN:NASANUMA 2013/04/16
CH'KD:KTAKAHASHI 2013/04/16
APPR:KMORIKAWA 2013/04/25
DESCRIPTION
REV A

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY	NASANUMA	DATE 2013/02/23
CHECKED BY	KTAKAHASHI	DATE 2013/02/23
APPROVED BY	KMORIKAWA	DATE 2013/03/15

TITLE: EMBOSS PACKAGED FOR 0.5MM FPC CONN ZIF S/T HOUSING ASSY

molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-52559-059
SHEET NO.: 3 OF 3
SIZE: A3

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